Lattice Semiconductor Corporation - LC5256MB-75F256C Datasheet

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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	2.3V ~ 2.7V
Number of Logic Elements/Blocks	8
Number of Macrocells	256
Number of Gates	-
Number of I/O	141
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5256mb-75f256c

Product Line	Ordering Part Number	Product Status	Reference PCN
LC5512MV	LC5512MV-45Q208C	Active / Orderable	
	LC5512MV-45QN208C		
	LC5512MV-75Q208C		
	LC5512MV-75QN208C		
	LC5512MV-75Q208I		
	LC5512MV-75QN208I		
	LC5512MV-45F256C		
	LC5512MV-45FN256C		
	LC5512MV-75F256C		
	LC5512MV-75FN256C		
	LC5512MV-75F256I		
	LC5512MV-75FN256I		
	LC5512MV-45F484C		
	LC5512MV-45FN484C		
	LC5512MV-75F484C		
	LC5512MV-75FN484C		
	LC5512MV-75F484I		
	LC5512MV-75FN484I		
LC5512MB	LC5512MB-45Q208C	**Discontinued**	PCN#09-10
	LC5512MB-45QN208C		
	LC5512MB-75Q208C		
	LC5512MB-75QN208C		
	LC5512MB-75Q208I		
	LC5512MB-75QN208I		
	LC5512MB-45F256C	Active / Orderable	
	LC5512MB-45FN256C		
	LC5512MB-75F256C		
	LC5512MB-75FN256C		
	LC5512MB-75F256I		
	LC5512MB-75FN256I		
	LC5512MB-45F484C	**Discontinued**	PCN#09-10
	LC5512MB-45FN484C		
	LC5512MB-75F484C		
	LC5512MB-75FN484C		
	LC5512MB-75F484I		
	LC5512MB-75FN484I		
LC5512MC	LC5512MC-45Q208C	**Discontinued**	PCN#09-10
	LC5512MC-45QN208C		
	LC5512MC-75Q208C		
	LC5512MC-75QN208C		
	LC5512MC-75Q208I		
	LC5512MC-75QN208I		
	LC5512MC-45F256C		
	LC5512MC-45FN256C		
	LC5512MC-75F256C		
	LC5512MC-75FN256C		
	LC5512MC-75F256I		
	LC5512MC-75FN256I		

ispXPLD™ 5000MX Family

3.3V, 2.5V and 1.8V In-System Programmable
eXpanded Programmable Logic Device XPLD™ Family

February 2010 **Data Sheet**

Features

- **Flexible Multi-Function Block (MFB) Architecture**
  - SuperWIDE™ logic (up to 136 inputs)
  - Arithmetic capability
  - Single- or Dual-port SRAM
  - FIFO
  - Ternary CAM
- **sysCLOCK™ PLL Timing Control**
  - Multiply and divide between 1 and 32
  - Clock shifting capability
  - External feedback capability
- **sysIO™ Interfaces**
  - LVCMOS 1.8, 2.5, 3.3V
    - Programmable impedance
    - Hot-socketing
    - Flexible bus-maintenance (Pull-up, pull-down, bus-keeper, or none)
    - Open drain operation
  - SSTL 2, 3 (I & II)
  - HSTL (I, III, IV)
  - PCI 3.3
  - GTL+
  - LVDS
  - LVPECL
  - LVTTL
- **Expanded In-System Programmability (ispXP™)**
  - Instant-on capability
  - Single chip convenience
  - In-System Programmable via IEEE 1532 Interface
  - Infinitely reconfigurable via IEEE 1532 or sysCONFIG™ microprocessor interface
  - Design security
- **High Speed Operation**
  - 4.0ns pin-to-pin delays, 300MHz f_{MAX}
  - Deterministic timing
- **Low Power Consumption**
  - Typical static power: 20 to 50mA (1.8V), 30 to 60mA (2.5/3.3V)
  - 1.8V core for low dynamic power
- **Easy System Integration**
  - 3.3V (5000MV), 2.5V (5000MB) and 1.8V (5000MC) power supply operation
  - 5V tolerant I/O for LVCMOS 3.3 and LVTTL interfaces
  - IEEE 1149.1 interface for boundary scan testing
  - sysIO quick configuration
  - Density migration
  - Multiple density and package options
  - PQFP and fine pitch BGA packaging
  - Lead-free package options

Table 1. ispXPLD 5000MX Family Selection Guide

	ispXPLD 5256MX	ispXPLD 5512MX	ispXPLD 5768MX	ispXPLD 51024MX
Macrocells	256	512	768	1,024
Multi-Function Blocks	8	16	24	32
Maximum RAM Bits	128K	256K	384K	512K
Maximum CAM Bits	48K	96K	144K	192K
sysCLOCK PLLs	2	2	2	2
t_{PD} (Propagation Delay)	4.0ns	4.5ns	5.0ns	5.2ns
t_S (Register Set-up Time)	2.2ns	2.8ns	2.8ns	3.0ns
t_{CO} (Register Clock to Out Time)	2.8ns	3.0ns	3.2ns	3.7ns
f_{MAX} (Maximum Operating Frequency)	300MHz	275MHz	250MHz	250MHz
Functional Gates	75K	150K	225K	300K
I/Os	141	149/193/253	193/317	317/381
Packages	256 fpBGA	208 PQFP 256 fpBGA 484 fpBGA	256 fpBGA 484 fpBGA	484 fpBGA 672 fpBGA

Table 12. ispXPLD 5000MX Supported I/O Standards

sysIO Standard	Nominal V_{CCO}	Nominal V_{REF}	Nominal V_{TT}
LVTTL	3.3V	N/A	N/A
LVCMOS-3.3	3.3V	N/A	N/A
LVCMOS-2.5	2.5V	N/A	N/A
LVCMOS-1.8	1.8V	N/A	N/A
PCI 3.3V	3.3V	N/A	N/A
AGP-1X	3.3V	N/A	N/A
SSTL3, Class I & II	3.3V	1.5V	1.5V
SSTL2, Class I & II	2.5V	1.25V	1.25V
CTT 3.3	3.3V	1.5V	1.5V
CTT 2.5	2.5V	1.25V	1.25V
HSTL, Class I	1.5V	0.75V	0.75V
HSTL, Class III	1.5V	0.9V	0.75V
HSTL, Class IV	1.5V	0.9V	0.75V
GTL+	N/A	1.0V	1.5V
LVPECL, Differential	2.5V, 3.3V	N/A	N/A
LVDS	2.5V, 3.3V	N/A	N/A

Table 13. Differential Interface Standard Support[1]

		sysIO Buffer
LVDS	Driver	Supported
	Receiver	Supported with standard termination
LVPECL	Driver	Supported with external resistor network
	Receiver	Supported with termination

1. For more information, refer to TN1000 – sysIO Usage Guidelines for Lattice Devices.

Control, Clock, sysCONFIG and JTAG Signals

Global clock pins support the same sysIO standards as general purpose I/O. When required the V_{REF} signal is derived from the adjacent bank. When differential standards are supported two adjacent clock pins are paired to form the input. The TOE, PROGRAM, CFG0 and DONE pins of the ispXPLD 5000MX device are the only pins that do not have sysIO capabilities. The JTAG TAP pins support only LVCMOS 3.3, 2.5 and 1.8V standards. The voltage is controlled by V_{CCJ}. These pins only support the LVTTL and LVCMOS standards applicable to the power supply voltage of the device. The global reset global output enable pins are associated with Bank 2 and support all of the sysIO standards.

Hotsocketing

The I/O on the ispXPLD 5000MX devices are well suited for those applications that require hot socketing capability, when configured as LVCMOS or LVTTL. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down device be minimal on active signals.

Programmable Drive Strength

The drive strength of I/Os that are programmed as LVCMOS is tightly controlled and can be programmed to a variety of different values. Thus the impedance an output driver can be closely match to the characteristic impedance of the line it is driving. This allows users to eliminate the need for external series termination resistors.

Absolute Maximum Ratings[1, 2, 3]

	ispXPLD 5000MC 1.8V	ispXPLD 5000MB/V 2.5V/3.3V
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V
PLL Supply Voltage (V_{CCP})	-0.5 to 2.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V
IEEE 1149.1 TAP Supply Voltage (V_{CCJ})	-0.5 to 4.5V	-0.5 to 4.5V
Input Voltage Applied[4, 5]	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C
Junction Temperature (T_J) with Power Applied	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied (while programming, following the programming specifications).
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and Undershoot of -2V to (V_{IHMAX} +2) volts not to exceed 6V is permitted for a duration of <20ns.
5. A maximum of 64 I/Os per device with V_{IN} > 3.6V is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Supply Voltage for 1.8V Devices (ispXPLD 5000MC)	1.65	1.95	V
	Supply Voltage for 2.5V Devices (ispXPLD 5000MB)	2.3	2.7	V
	Supply Voltage for 3.3V Devices (ispXPLD 5000MV)	3	3.6	V
V_{CCP}	PLL Block Supply Voltage for PLL 1.8V Devices	1.65	1.95	V
	PLL Block Supply Voltage for PLL 2.5V Devices	2.3	2.7	V
	PLL Block Supply Voltage for PLL 3.3V Devices	3	3.6	V
T_J	Junction Temperature (Commercial Operation)	0	90	C
	Junction Temperature (Industrial Operation)	-40	105	C

E²CMOS Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle[1]	1,000	—	Cycles

1. Valid over commercial temperature range.

Hot Socketing Characteristics[1, 2, 3, 4]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	0 ð V_{IN} ð 3.0V	—	+/-50	+/-800	µA

1. Insensitive to sequence of V_{CC} and V_{CCO} when V_{CCO}þð 1.0V. For V_{CCO} > 1.0V, V_{CC} min must be present. However, assumes monotonic rise/fall rates for V_{CC} and $V_{CCO,}$ provided (V_{IN} - V_{CCO})þð 3.6V.
2. 0 ð V_{CC} ð V_{CC} (MAX), 0 ð V_{CCO} ð V_{CCO} (MAX)
3. I_{DK} is additive to I_{PU}, I_{PD} or I_{BH}. Device defaults to pull-up until non-volatile cells are active.
4. LVTTL, LVCMOS only.

sysIO Recommended Operating Conditions

Standard	V_{CCO} (V)[2]			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.0	3.3	3.6	—	—	—
LVCMOS 2.5	2.3	2.5	2.7	—	—	—
LVCMOS 1.8[1]	1.65	1.8	1.95	—	—	—
LVTTL	3.0	3.3	3.6	—	—	—
PCI 3.3	3.0	3.3	3.6	—	—	—
AGP-1X	3.15	3.3	3.45	—	—	—
SSTL 2	2.3	2.5	2.7	1.15	1.25	1.35
SSTL 3	3.0	3.3	3.6	1.3	1.5	1.7
CTT 3.3	3.0	3.3	3.6	1.35	1.5	1.65
CTT 2.5	2.3	2.5	2.7	1.35	1.5	1.65
HSTL Class I	1.4	1.5	1.6	0.68	0.75	0.9
HSTL Class III	1.4	1.5	1.6	—	0.9	—
HSTL Class IV	1.4	1.5	1.6	—	0.9	—
GTL+	1.4	—	3.6	0.882	1.0	1.122
LVDS	2.3	2.5/3.3	3.6	—	—	—

1. Design tools default setting.
2. Inputs are independent of V_{CCO} setting. However, V_{CCO} must be set within the valid operating range for one of the supported standards.

ispXPLD 5000MX Family External Switching Characteristics [1, 2, 3]

Over Recommended Operating Conditions

Parameter	Description	-4		-45		-5		-52		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{PD}	Data Propagation Delay, 5-PT Bypass	—	4.0	—	4.5	—	5.0	—	5.2	—	7.5	ns
t_{PD_PTSA}	Data propagation delay	—	4.8	—	5.7	—	6.0	—	6.5	—	9.5	ns
t_S	MFB Register Setup Time Before Clock, 5-PT Bypass	2.2	—	2.8	—	2.8	—	3.0	—	4.5	—	ns
t_{S_PTSA}	MFB Register Setup Time Before Clock	2.5	—	3.1	—	3.1	—	3.6	—	5.5	—	ns
t_{SIR}	MFB Register Setup Time Before Clock, Input Register Path	1.0	—	1.0	—	1.0	—	0.5	—	1.7	—	ns
t_H	MFB Register Hold Time Before Clock, 5-PT Bypass	0.0	—	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{H_PTSA}	MFB Register Hold Time Before Clock	0.0	—	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	MFB Register Hold Time Before Clock, Input Register Path	0.5	—	0.5	—	0.5	—	1.0	—	1.3	—	ns
t_{CO}	MFB Register Clock-to-Output Delay	—	2.8	—	3.0	—	3.2	—	3.7	—	5.0	ns
t_R	External Reset Pin to Output Delay	—	4.0	—	4.5	—	5.0	—	5.0	—	7.5	ns
t_{RW}	Reset Pulse Duration	1.8	—	1.8	—	1.8	—	2.0	—	3.0	—	ns
$t_{LPTOE/DIS}$	Input to Output Local Product Term Output Enable/Disable	—	6.0	—	7.0	—	7.5	—	8.5	—	10.5	ns
$t_{SPTOE/DIS}$	Input to Output Shared Product Term Output Enable/Disable	—	6.0	—	7.0	—	7.5	—	8.5	—	10.5	ns
$t_{GOE/DIS}$	Global OE Input to Output Enable/Disable	—	4.5	—	5.5	—	5.5	—	6.5	—	7.5	ns
t_{CW}	Clock Width, High or Low	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{GW}	Gate Width Low (for Low Transparent) or High (for High Transparent)	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{WIR}	Input Register Clock Width, High or Low	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{SKEW}	Clock-to-Out Skew, Block Level	—	0.6	—	0.6	—	0.6	—	0.6	—	1.0	ns
f_{MAX} [4]	Clock Frequency with Internal Feedback	—	300	—	275	—	250	—	250	—	150	MHz
f_{MAX} (Ext.)	Clock Frequency with External Feedback, $1/(t_S + t_{CO})$	—	200	—	171	—	166	—	149	—	105	MHz
f_{MAX} (Tog.)	Clock Frequency Max. Toggle	—	333	—	333	—	333	—	277	—	200	MHz
f_{MAX} (CAMC)[5]	Clock Frequency to CAM (Configure Mode)	—	280	—	280	—	230	—	230	—	168	MHz
f_{MAX} (CAM)[5]	Clock Frequency to CAM (Compare Mode)	—	150	—	150	—	150	—	135	—	90	MHz

ispXPLD 5000MX Family External Switching Characteristics (Continued)[1, 2, 3]

Over Recommended Operating Conditions

Parameter	Description	-4		-45		-5		-52		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
f_{MAX} (RAM)[5]	Clock Frequency to RAM in:											
	Single Port Mode	—	155	—	155	—	155	—	155	—	93	MHz
	Dual Port Mode	—	155	—	155	—	155	—	155	—	93	MHz
	Pseudo Dual Port Mode	—	180	—	180	—	160	—	160	—	106	MHz
f_{MAX} (FIFO)[5]	Clock Frequency to FIFO	—	225	—	220	—	210	—	210	—	132	MHz
t_{PWR_ON}	Power-on Time	—	200	—	200	—	200	—	200	—	200	µs

Timing v.1.8

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate timing for other standards.
2. Measured using standard switching circuit, global routing loading of 1, worst case PTSA loading and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using GRP feedback.
5. CAM, FIFO, RAM f_{MAX} specification used shared PT Clk.

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

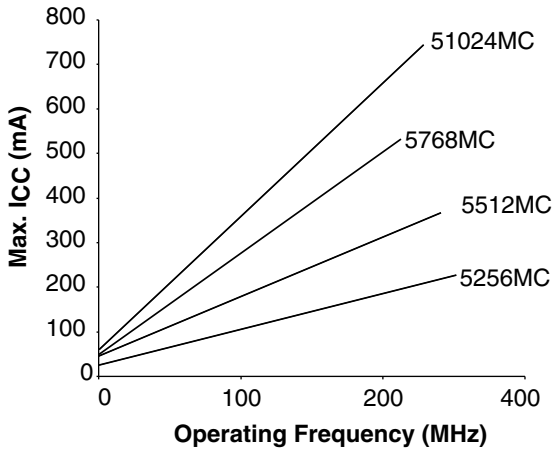
Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
$t_{CAMWMSKS}$	Write Mask Register Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMWMSKH}$	Write Mask Register Setup Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMRSTO}$	Reset to CAM Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
$t_{CAMRSTR}$	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
$t_{CAMRSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
CAM – Compare Mode													
$t_{CAMDATAS}$	Data Setup Time before Clock	—	-0.41	—	-0.41	—	-0.33	—	-0.33	—	-0.31	—	ns
$t_{CAMDATAH}$	Data Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMENMSKS}$	Enable Mask Register Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMENMSKH}$	Enable Mask Register Setup Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMCASC}$	CAM Width Expansion Delay	—	—	0.40	—	0.40	—	0.50	—	0.50	—	0.51	ns
t_{CAMCO}	Clock to Output (Address Out) Delay	—	—	6.19	—	6.13	—	6.81	—	6.61	—	9.63	ns
$t_{CAMMATCH}$	Clock to Match Flag Delay	—	—	6.19	—	6.13	—	6.07	—	6.61	—	10.22	ns
$t_{CAMMMATCH}$	Clock to Multi-Match Flag Delay	—	—	5.50	—	5.50	—	6.38	—	6.38	—	7.72	ns
$t_{CAMRSTFLAG}$	CAM Reset to Flags Delay	—	—	3.16	—	3.16	—	3.95	—	3.95	—	4.11	ns
Single Port RAM													
$t_{SPADDDATA}$	Address to Data Delay	—	—	5.97	—	5.97	—	5.97	—	5.97	—	7.76	ns
t_{SPMSS}	Memory Select Setup Before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{SPMSH}	Memory Select Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{SPCES}	Clock Enable Setup before Clock Time	—	2.30	—	2.30	—	2.30	—	2.30	—	9.80	—	ns
t_{SPCEH}	Clock Enable Hold time after Clock Time	—	-2.95	—	-2.95	—	-2.95	—	-2.95	—	-2.27	—	ns
t_{SPADDS}	Address Setup before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns

ispXPLD 5000MX Family Timing Adders

Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{IOI} Input Adjusters													
LVTTL_in	Using 3.3V TTL	t_{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS_18_in	Using 1.8V CMOS	t_{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS_25_in	Using 2.5V CMOS	t_{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS_33_in	Using 3.3V CMOS	t_{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_in	Using AGP 1x	t_{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
CTT25_in	Using CTT 2.5V	t_{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
CTT33_in	Using CTT 3.3V	t_{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
GTL+_in	Using GTL+	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_I_in	Using HSTL 2.5V, Class I	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_III_in	Using HSTL 2.5V, Class III	t_{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
HSTL_IV_in	Using HSTL 2.5V, Class IV	t_{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVDS_in	Using Low Voltage Differential Signaling (LVDS)	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
LVPECL_in	Using Low Voltage PECL	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
PCI_in	Using PCI	t_{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
SSTL2_I_in	Using SSTL 2.5V, Class I	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL2_II_in	Using SSTL 2.5V, Class II	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_in	Using SSTL 3.3V, Class I	t_{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
SSTL3_II_in	Using SSTL 3.3V, Class II	t_{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
t_{IOO} Output Adjusters – Output Signal Modifiers													
Slow Slew	Using Slow Slew (LVTTL and LVCMOS Outputs Only)	t_{IOBUF}, t_{IOEN}	—	0.9	—	0.9	—	0.9	—	0.9	—	0.9	ns
t_{IOO} Output Adjusters – Output Configurations													
LVTTL_out	Using 3.3V TTL Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVCMOS_18_4mA_out	Using 1.8V CMOS Standard, 4mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
LVCMOS_18_5.33mA_out	Using 1.8V CMOS Standard, 5.33mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns

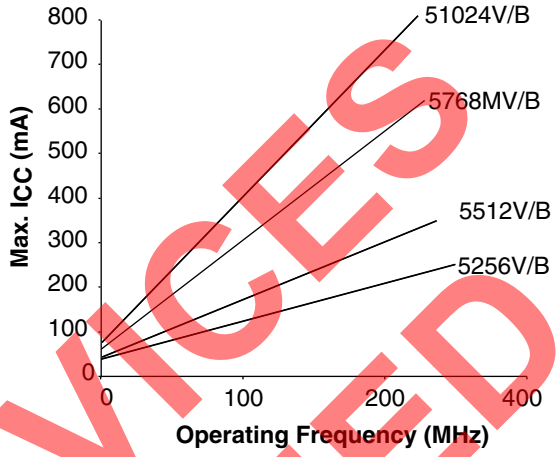
Power Consumption

ispXPLD 5000MC Typical I_{CC} vs. Frequency



Note: The device is configured with maximum number of 16-bit counters, no PLL, typical current at 1.8V, 25°C.

ispXPLD 5000MV/B Typical I_{CC} vs. Frequency



Note: The device is configured with maximum number of 16-bit counters, no PLL, typical current at 3.3V (MV) or 2.5V (MB), 25°C.

Power Estimation Coefficients

Device	K0	K1	K2	K3	K4	K5	K6	K7	DC	
									ispXPLD 5000MC	ispXPLD 5000MV/B
ispXPLD 5256	2.2	8.4	7	12	100	0.1379	0.0433	6.476	16	24
ispXPLD 5512	2.2	8.4	9.4	18	151	0.1379	0.0433	6.476	17	25
ispXPLD 5768	2.2	8.4	10.2	21	170	0.1379	0.0433	6.476	27	36
ispXPLD 51024	2.2	8.4	13	27.6	200	0.1379	0.0433	6.476	35	43

Note: For further information about the use of these coefficients, refer to TN1031 – Power Estimation in ispXPLD 5000MX Devices.

Memory Coefficients

Device	K8	K9	K10	K11
ispXPLD 5256	0.004719	0.0924	4.4	2.9
ispXPLD 5512	0.004719	0.0924	4.4	2.9
ispXPLD 5768	0.004719	0.0924	4.4	2.9
ispXPLD 51024	0.004719	0.0924	4.4	2.9

- K0 = Current per MFB input (µA/MHz)
- K1 = Current per Product Term (µA/MHz)
- K2 = Current per GRP from MFB (µA/MHz)
- K3 = Current per GRP from I/O (µA/MHz)
- K4 = Global clock tree current (µA/MHz)
- K5 = PLL digital (mA/MHz)
- K6 = PLL analog (mA/MHz)
- K7 = PLL analog baseline (mA)
- DC = Baseline current at 0Mhz (mA)
- K8 = CAM frequency component (mA/MHz)
- K9 = CAM DC component (mA)
- K10 = Current per row decoder (µA/MHz)
- K11 = Current per column driver (µA/MHz)

Signal Descriptions

Signal Names	Descriptions
TMS	Input – This pin is the Test Mode Select input, which is used to control the IEEE 1149.1 state machine.
TCK	Input – This pin is the Test Clock input pin, used to clock the IEEE 1149.1 state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data in pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data out pin used to shift data out.
TOE	Input – Test Output Enable pin. TOE tristates all I/O pins when driven low.
GOE0, GOE1	Input – Global output enable inputs.
RESET	Input – This pin resets all the registers in the device. The global polarity for this pin is selectable on a global basis.þ The default is active low. An external pull-down is required when polarity is set to active high.
yzz	Input/Output – These are the general purpose I/O used by the logic array. *y* is the MFB reference (alpha) and z is the macrocell reference (numeric) y: A-X (768 macrocells) y: A-P (512 macrocells) y: A-H (256 macrocells) z: 0-31
GND	GND – Ground
NC	No connect
V_{CC}	V_{CC} – The power supply pins for core logic.
V_{CCO0}, V_{CCO1}, V_{CCO2}, V_{CCO3}	V_{CC} – The power supply pins for I/O banks 0, 1, 2, and 3.
V_{REF0}, V_{REF1}, V_{REF2}, V_{REF3}	Input – This pin defines the reference voltage for I/O banks 0, 1, 2, and 3.
GCLK0, GCLK1, GCLK2, GCLK3	Input – Global clock/clock enable inputs (see Figure 14 for differential pairing).
CLK_OUT0, CLK_OUT1	Output – Optional clock output from PLL 0 and 1.
PLL_RST0, PLL_RST1	Input – Optional input resets the M divider in PLL 0 and 1.
PLL_FBK0, PLL_FBK1	Input – Optional feedback input for PLL 0 and 1.
GNDP	GND – Ground for PLLs.
V_{CCP}	V_{CC} – The power supply pin for PLLs.
V_{CCJ}	V_{CC} – The power supply for the IEEE 1149.1 interface.
DATA*x*	I/O – sysCONFIG data pins, bit *x*.
CSB	Input – sysCONFIG interface chip select. Drive low to select sysCONFIG interface.
CFG0	Input – Defines SRAM configuration mode. Low: sysCONFIG port, high: E^2CMOS or IEEE 1149.1 TAP.
PROGRAMB	Input – Controls the programming of SRAM. Hold high for normal operation. Toggle low to reload SRAM from E^2 memory.
CCLK[1]	Input – Clock for sysCONFIG interface. Reads and writes occur on the rising edge of the clock.
READ[1]	Input – Drive high to perform reads from the sysCONFIG interface.
INITB	I/O – Indicates status of configuration. Can be driven low to inhibit configuration.
DONE	Output (open drain) – Indicates status of configuration.

1. These inputs should not toggle during power up for proper power-up configuration.

ispXPLD 5256MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	256 fpBGA Ball Number
			Macrocell 1	Macrocell 2		
1	4N	A16/CSB	A9	B9	A17	L5
1	5P	A18/READ	A10	B10	A19	N1
1	5N	A20/CCLK	A11	B11	A21	M2
-	-	VCC	-	-	-	VCC
-	-	DONE	-	-	-	M4
1	6P	A22	A12	B12	A23	N3
1	6N	A24	A13	B13	A25	P4
1	7P	A26	A14	B14	A27	N5
1	7N	A28	A15	B15	A29	M6
-	-	PROGRAMB	-	-	-	R3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)
-	-	VCCO1	-	-	-	VCC01
-	-	CFG0	-	-	-	L8
1	8P	B2	A16	B16	B3	T7
1	8N	B4	A17	B17	-	R7
1	9P	B5	A18	B18	-	N7
1	9N	B6	A19	B19	B7	P7
1	10P	B8	A20	B20	B9	T8
1	10N	B10	A21	B21	B11	R8
1	11P	B12	A22	B22	B13	M8
1	11N	B14	A23	B23	B15	P8
1	-	B16/VREF1	-	-	B17	L9
1	12P	B18	A24	B24	B19	N8
1	12N	B20	A25	B25	-	M9
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)
1	13P	B21	A26	B26	-	N10
-	-	VCCO1	-	-	-	VCCO1
1	13N	B22	A27	B27	B23	T9
1	14P	B24	A28	B28	B25	T10
1	14N	B26	A29	B29	B27	R9
-	-	VCC	-	-	-	VCC
1	15P	B28	A30	B30	B29	P9
1	15N	B30	A31	B31	B31	N9
2	16P	C0	C0	D0	C1	T11
2	16N	C2	C1	D1	C3	T12
2	17P	C4	C2	D2	-	P10
2	17N	C5	C3	D3	-	R10
2	18P	C6	C4	D4	C7	R11
-	-	VCCO2	-	-	-	VCCO2
2	18N	C8	C5	D5	C9	M10
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)
2	19P	C10	C6	D6	C11	M11
2	19N	C12	C7	D7	C13	T13

ispXPLD 5256MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	256 fpBGA Ball Number
			Macrocell 1	Macrocell 2		
3	51N	F2	E1	F1	F3	B8
3	51P	F0	E0	F0	F1	C8
0	52N	G30	G31	H31	G31	B7
0	52P	G28	G30	H30	G29	A7
-	-	GND	-	-	-	NC
0	53N	G26	G29	H29	G27	D7
0	53P	G24	G28	H28	G25	C7
0	54N	G22	G27	H27	G23	B6
-	-	VCCO0	-	-	-	VCCO0
0	54P	G21	G26	H26	-	E7
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)
0	55N	G20	G25	H25	-	E6
0	55P	G18	G24	H24	G19	A6
0	56N	G16/VREF0	G3	H3	G17	A5
0	56P	G14	G2	H2	G15	A4
0	57N	G12	G23	H23	G13	B5
0	57P	G10	G22	H22	G11	A3
0	58N	G8	G21	H21	G9	B4
0	58P	G6	G20	H20	G7	B3
0	59N	G5	G19	H19	-	C5
0	59P	G4	G18	H18	-	C6
0	60N	G2	G1	H1	G3	D5
0	60P	G0	G0	H0	G1	D6
-	-	VCCO0	-	-	-	VCCO0
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
0	96N	M12	M23	O23	M13	196	B5	A10
0	96P	M10	M22	O22	M11	197	A3	A9
0	97N	M8	M21	O21	M9	198	B4	C9
0	97P	M6	M20	O20	M7	199	B3	D9
0	98N	M5	M19	O19	—	200	C5	F9
0	98P	M4	M18	O18	—	201	C6	E9
0	99N	M2	M1	O1	M3	202	D5	A8
—	—	V_{CCO0}	—	—	—	—	V_{CCO0}	V_{CCO0}
0	99P	M0	M0	O0	M1	203	D6	B8
—	—	GND (Bank 0)	—	—	—	—	GND (Bank 0)	GND (Bank 0)
0	100N	N30	O29	—	N31	—	—	A7
0	100P	N28	O28	—	N29	—	—	B7
0	101N	N26	O27	—	N27	—	—	A5
0	101P	N24	O26	—	N25	—	—	B5
0	102N	N22	O25	—	N23	—	—	B6
0	102P	N21	O24	—	—	—	—	C7
0	103N	N20	O23	—	—	—	—	E8
0	103P	N18	O22	—	N19	—	—	E7
0	104N	N16	O21	—	N17	—	—	E6
0	104P	N14	O20	—	N15	—	—	D6
0	105N	N12	O19	—	N13	—	—	D8
—	—	V_{CCO0}	—	—	—	204	V_{CCO0}	V_{CCO0}
0	105P	N10	O18	—	N11	—	—	F8
—	—	GND (Bank 0)	—	—	—	205	GND (Bank 0)	GND (Bank 0)
0	106N	N8	O17	—	N9	—	—	F7
0	106P	N6	O16	—	N7	—	—	D7
0	107N	N5	O15	—	—	206	A2	C6
0	107P	N4	O14	—	—	207	B2	C5
0	108N	N2	O13	—	N3	—	—	C4
0	108P	N0	O12	—	N1	—	—	D5

1. Not available for differential pair.

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
3	76P	L30/PLL_FBK1	L0	J0	L31	F15	E21
3	77N	M0/PLL_RST1	P27	N27	M1	H12	G22
3	77P	M2	P26	N26	M3	G14	F21
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	78N	M4	P25	N25	M5	F16	H21
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	78P	M6	P24	N24	-	E16	G21
-	-	GND	-	-	-	GND	GND
3	79N	M8	P23	N23	M9	G13	D22
3	79P	M10	P22	N22	M11	G12	D21
3	80N	M12	P21	N21	M13	F14	J20
3	80P	M14/CLK_OUT1	P20	N20	M15	E15	J19
3	81N	M16	N31	-	M17	F12	E20
-	-	VCC	-	-	-	VCC	VCC
3	81P	M18	N30	M30	M19	F13	F20
3	82N	M20	N29	M28	M21	D16	H17
3	82P	M22	N28	M26	M23	D15	H18
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	83N	M24	N27	-	M25	—	J18
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	83P	M26	N26	-	M27	—	H19
3	84N	M28	N25	-	M29	—	G20
3	84P	M30	N24	-	M31	—	G19
-	-	GND	-	-	-	GND	GND
3	85N	N0	N23	-	N1	—	C22
-	-	VCC	-	-	-	VCC	VCC
3	85P	N2	N22	-	N3	—	C21
3	86N	N4	N21	-	-	—	D20
3	86P	N6	N20	-	-	—	C19
3	87N	N8	N19	-	N9	C16	F19
3	87P	N10	N18	-	N11	B16	E19
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	88N	N12	N17	-	N13	C15	G18
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	88P	N14	N16	-	N15	B15	F18
3	89N	N16	N15	-	N17	E14	B20
3	89P	N18	N14	-	N19	D14	B19
3	90N	N20	N13	-	N21	E13	A20
3	90P	N22	N12	-	N23	A15	A19
3	91N	N24	P19	N19	N25	D12	D18
3	91P	N26	P18	N18	N27	B14	C18
3	92N	N28	P17	N17	N29	C13	G17
3	92P	N30	P16	N16	N31	A14	F16

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
2	63P	K8	L20	-	K9	AA19	AA18
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	63N	K10	L21	-	K11	U17	Y18
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	64P	K12	L22	-	K13	V18	AD25
2	64N	K14	L23	-	K15	AB21	AD26
2	65P	K16	L24	-	K17	U18	AC23
2	65N	K18	L25	-	K19	T17	AC24
2	66P	K20	L26	-	K21	AB20	AC25
2	66N	K22	L27	-	K23	AA20	AC26
2	67P	K24	L28	-	K25	Y19	AB22
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	67N	K26	L29	-	K27	V19	AB23
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	68P	K28	J16	L16	K29	T18	AB24
2	68N	K30	J17	L17	K31	R17	AB25
2	69P	L0	J18	L18	L1	U19	AB26
2	69N	L2	J19	L19	L3	T19	AA26
2	70P	L4	L30	I24	L5	V20	AA22
-	-	VCC	-	-	-	VCC	VCC
2	70N	L6	L31	I26	L7	U20	Y21
2	71P	L8	J20	L20	L9	W20	AA23
2	71N	L10	J21	L21	L11	Y21	AA24
2	72P	L12	J22	L22	L13	R18	AA25
2	72N	L14	J23	L23	L15	R19	Y26
-	-	GND	-	-	-	GND	GND
2	73P	L16	J24	L24	L17	W21	Y22
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	73N	L18	J25	L25	L19	Y22	Y23
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	74P	L20	J26	L26	L21	R20	W20
2	74N	L22	J27	L27	L23	P20	V20
2	75P	L24	J28	L28	L25	T21	W21
2	75N	L26	J29	L29	L27	R21	V21
2	76P	L28	J30	L30	L29	U21	Y24
2	76N	L30	J31	L31	L31	V21	Y25
2	77P	N0	P0	N0	N1	—	W22
2	77N	N2	P1	N1	N3	—	W23
2	78P	N4	P2	N2	N5	—	W24
-	-	VCC	-	-	-	VCC	VCC
2	78N	N6	P3	N3	N7	—	W25
-	-	GND	-	-	-	GND	GND
2	79P	N8	P4	N4	N9	—	W26

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	110N	U4	X25	V25	U5	H21	J21
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	110P	U6	X24	V24	U7	G21	H21
-	-	GND	-	-	-	GND	GND
3	111N	U8	X23	V23	U9	D22	G25
3	111P	U10	X22	V22	U11	D21	G24
3	112N	U12	X21	V21	U13	J20	G23
3	112P	U14/CLK_OUT1	X20	V20	U15	J19	G22
3	113N	U16	V31	-	U17	E20	J20
-	-	VCC	-	-	-	VCC	VCC
3	113P	U18	V30	U30	U19	F20	H20
3	114N	U20	V29	U28	U21	H17	G26
3	114P	U22	V28	U26	U23	H18	F25
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	115N	U24	V27	-	U25	J18	F24
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	115P	U26	V26	-	U27	H19	F23
3	116N	U28	V25	-	U29	G20	G21
3	116P	U30	V24	-	U31	G19	F22
-	-	GND	-	-	-	GND	GND
3	117N	V0	V23	-	V1	C22	F26
-	-	VCC	-	-	-	VCC	VCC
3	117P	V2	V22	-	V3	C21	E26
3	118N	V4	V21	-	V5	D20	E25
3	118P	V6	V20	-	V7	C19	E24
3	119N	V8	V19	-	V9	F19	E23
3	119P	V10	V18	-	V11	E19	E22
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	120N	V12	V17	-	V13	G18	D26
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	120P	V14	V16	-	V15	F18	D25
3	121N	V16	V15	-	V17	B20	D24
3	121P	V18	V14	-	V19	B19	D23
3	122N	V20	V13	-	V21	A20	C26
3	122P	V22	V12	-	V23	A19	C25
3	123N	V24	X19	V19	V25	D18	G19
3	123P	V26	X18	V18	V27	C18	F19
3	124N	V28	X17	V17	V29	G17	G18
3	124P	V30	X16	V16	V31	F16	F18
3	125N	W0	X31	V31	W1	E17	F20
3	125P	W2	X30	V30	W3	D17	E20
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
3	126N	W4	V11	U21	W5	B18	E19
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	126P	W6	V10	U20	W7	A18	E18
-	-	GND	-	-	-	GND	GND
3	127N	W8	V9	U18	W9	C17	C24
-	-	VCC	-	-	-	VCC	VCC
3	127P	W10	V8	U16	W11	B17	C23
3	128N	W12	V7	U12	W13	C16	D22
3	128P	W14	V6	U10	W15	B16	D21
3	129N	W16	V5	U8	W17	F13	E21
3	129P	W18	V4	U6	W19	F15	D20
3	130N	W20	V3	U5	W21	D16	D19
3	130P	W22	V2	U4	W23	E16	D18
3	131N	W24	V1	U2	W25	A16	C22
3	131P	W26	V0	U0	W27	A15	C21
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	132N	W28	X15	V15	W29	B15	C20
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	132P	W30	X14	V14	W31	A14	C19
3	133N	X0	X13	V13	X1	D15	C18
3	133P	X2	X12	V12	X3	E15	C17
3	134N	X4	X11	V11	X5	D14	B24
3	134P	X6	X10	V10	X7	F14	B23
3	135N	X8	X9	V9	X9	A13	B22
3	135P	X10	X8	V8	X11	B13	B21
3	136N	X12/VREF3	X29	V29	X13	C14	B20
3	136P	X14	X28	V28	X15	E14	B19
3	137N	X16	X7	V7	X17	E13	B18
3	137P	X18	X6	V6	X19	F12	B17
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	138N	X20	X5	V5	X21	D13	A24
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	138P	X22	X4	V4	X23	C13	A23
3	139N	X24	X3	V3	X25	E12	A22
-	-	GND	-	-	-	GND	GND
3	139P	X26	X2	V2	X27	C12	A21
-	-	VCC	-	-	-	VCC	VCC
3	140N	X28	X1	V1	X29	B12	A20
3	140P	X30	X0	V0	X31	A12	A19
0	141N	Y30	Y31	AA31	Y31	E11	A18
-	-	VCC	-	-	-	VCC	VCC
0	141P	Y28	Y30	AA30	Y29	C11	A17
-	-	GND	-	-	-	GND	GND

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
December 2003	07	Added ispXPLD 5768MX information (supply current, timings, power consumption, power estimation coefficients, memory coefficients, logic signal connections, ordering part numbers).
		Updated ispXPLD 5000MX timing numbers (version v.1.7).
		Added lead-free package designator.
		Removed ispXPLD 5000MC industrial temperature grade ordering part numbers.
January 2004	08	Lead-free package release for the ispXPLD 5000MC and 5000MV devices.
		Timing model parameter tCOi correction - Maximum specification instead of Minimum (no changes in the timing numbers).
March 2004	08.1	Updated the MFB Cascade Chain table for the ispXPLD 5256MX device.
May 2004	09	Updated the ispXPLD 5000MX timig numbers (version v.1.8) ispXPLD 5256MC, 5512MC and 51024MC industrial temperature grade devices release
		Updated typical supply current data and condition.
		ispXPLD 5256MX 256-fpBGA logic signal connection tables: Removed internal signal description for ball H5 and G14.
August 2004	10	Added footnote "1, page 49. These inputs should not toggle during power up for proper power-up configuration." to CCLK and READ.
		Added ispXPLD 5768MC Industrial grade OPNs (Conventional and Lead-Free).
October 2004	10.1	Figure 19, LVPECL Driver with Three Resistor Pack has been updated (ispXPLD LVPECL Buffer changed to ispXPLD Emulated LVPECL Buffer)
November 2004	11	Added ispXPLD 5000MB (2.5V) Lead-Free Ordering Part Numbers.
December 2004	11.1	Pin name RESETB has been updated to RESET.
March 2005	12	208-PQFP Lead-free package release for the ispXPLD 5512MV/B/C devices.
April 2005	12.1	Page 23, clarification of footnote regarding IDK specification.
March 2006	12.2	Signal description for RESET has been updated.
April 2009	12.3	Ordering Information section has been updated to describe alternate LC5768MB/MV top side marking format.
February 2010	12.4	References to "system gates" changed to "functional gates."